SiS110DN **Vishay Siliconix** 

www.vishay.com

N-Channel 100 V (D-S) MOSFET



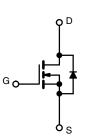
PRODUCT SUMMARY	
V <sub>DS</sub> (V)	100
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS}$ = 10 V	0.054
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS}$ = 7.5 V	0.070
Q <sub>g</sub> typ. (nC)	6.5
I <sub>D</sub> (A)	14.2 <sup>g</sup>
Configuration	Single

#### **FEATURES**

- TrenchFET<sup>®</sup> Gen IV power MOSFET
- Tuned for the lowest R<sub>DS</sub> Q<sub>oss</sub> FOM
- 100 % R<sub>q</sub> and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

#### **APPLICATIONS**

- · Primary side switch
- DC/DC converter
- Motor drive switch
- Boost converter
- LED backlighting



N-Channel MOSFET

# **ORDERING INFORMATION**

Package	PowerPAK 1212-8
Lead (Pb)-free and halogen-free	SiS110DN-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C, un PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V <sub>DS</sub>	100		
Gate-source voltage		V <sub>GS</sub>	± 20	V	
Continuous drain current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C		14.2		
	T <sub>C</sub> = 70 °C	1. [	11.4		
	T <sub>A</sub> = 25 °C	I <sub>D</sub>	5.2 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C	1 –	4.2 <sup>b, c</sup>		
Pulsed drain current (t = 100 µs)		I <sub>DM</sub>	20	— A	
	T <sub>C</sub> = 25 °C		16 <sup>a</sup>		
Continuous source-drain diode current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	2.6 <sup>b, c</sup>		
Single pulse avalanche current		I <sub>AS</sub>	10		
Single pulse avalanche energy $L = 0.1 \text{ mH}$		E <sub>AS</sub>	5	mJ	
	T <sub>C</sub> = 25 °C		24		
Maniana a successibilitation	T <sub>C</sub> = 70 °C		15	14/	
Maximum power dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.2 <sup>b, c</sup>	W	
	T <sub>A</sub> = 70 °C	1	2.1 <sup>b, c</sup>		
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Soldering recommendations (peak temperature) d, e		Ĭ	260		

THERMAL RESISTANCE RATING	GS				
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient b, f	t ≤ 10 s	R <sub>thJA</sub>	31	39	°C/W
Maximum junction-to-case (drain)	Steady state	R <sub>thJC</sub>	4.2	5.2	C/W

#### Notes

a. Package limited

b. Surface mounted on 1" x 1" FR4 board

t = 10 s c.

d. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK 1212-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection

e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

f. Maximum under steady state conditions is 81 °C/W

T<sub>C</sub> = 25 °C g.

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HALOGEN

FREE



SiS110DN

Vishay Siliconix

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static				•		
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_{D} = 250 \mu A$	100	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	l <sub>D</sub> = 10 mA	-	57	-	
V <sub>GS(th)</sub> temperature coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA	-	-7.2	-	mV/°C
Gate-source threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	2	-	4	V
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	-	-	100	nA
7		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V	-	-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 70 ^{\circ}\text{C}$	-	-	10	μA
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	10	-	-	Α
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 4 \text{ A}$	-	0.045	0.054	Ω
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 7.5 \text{ V}, I_D = 4 \text{ A}$	-	0.050	0.070	
Forward transconductance <sup>a</sup>	g <sub>fs</sub>	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 10 \text{ A}$	-	25	-	S
Dynamic <sup>b</sup>				•		
Input capacitance	C <sub>iss</sub>		-	550	-	pF
Output capacitance	C <sub>oss</sub>	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	50	-	
Reverse transfer capacitance	C <sub>rss</sub>		-	7	-	1
Table also de ser	0	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}$	-	8.5	13	
Total gate charge	Qg		-	6.5	10	nC
Gate-source charge	Q <sub>gs</sub>	$V_{DS}$ = 50 V, $V_{GS}$ = 7.5 V, $I_D$ = 4 A	-	2.5	-	
Gate-drain charge	Q <sub>gd</sub>		-	1.5	-	
Output charge	Q <sub>oss</sub>	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}$	-	8	-	
Gate resistance	Rg	f = 1 MHz	0.3	1.3	2.6	Ω
Turn-on delay time	t <sub>d(on)</sub>		-	10	20	
Rise time	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, \text{ R}_{\text{I}} = 12.5 \Omega, \text{ I}_{\text{D}} \cong 4 \text{ A},$	-	5	10	
Turn-off delay time	t <sub>d(off)</sub>	$V_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$	-	14	30	
Fall time	t <sub>f</sub>		-	5	10	1
Turn-on delay time	t <sub>d(on)</sub>		-	11	20	ns
Rise time	tr	$V_{DD} = 50 \text{ V}, \text{ R}_{L} = 12.5 \Omega, \text{ I}_{D} \cong 4 \text{ A},$	-	5	10	_
Turn-off delay time	t <sub>d(off)</sub>	$V_{\text{GEN}} = 7.5 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$	-	14	30	
Fall time	t <sub>f</sub>		-	5	10	1
Drain-Source Body Diode Characterist	ics		•			
Continuous source-drain diode current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	-	-	16	
Pulse diode forward current	I <sub>SM</sub>		-	-	20	A
Body diode voltage	V <sub>SD</sub>	$I_S = 4$ A, $V_{GS} = 0$ V	-	0.85	1.2	V
Body diode reverse recovery time	t <sub>rr</sub>		-	50	100	ns
Body diode reverse recovery charge	Q <sub>rr</sub>		-	53	110	nC
Reverse recovery fall time	ta	$I_F = 4 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^\circ\text{C}$	-	27	-	
Reverse recovery rise time	t <sub>b</sub>		-	23	-	ns

Notes

a. Pulse test: pulse width  $\leq 300~\mu\text{s},$  duty cycle  $\leq 2~\%$ 

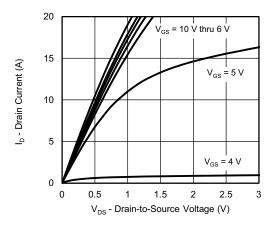
b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

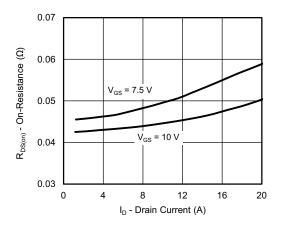
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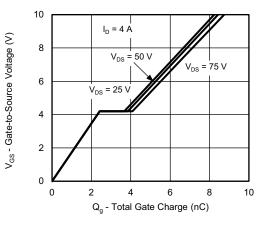
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



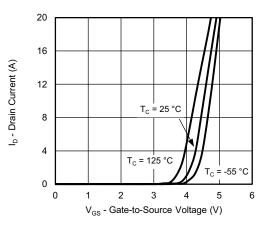
**Output Characteristics** 



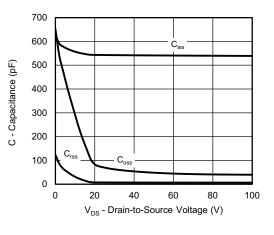
**On-Resistance vs. Drain Current and Gate Voltage** 



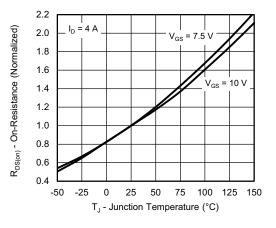
Gate Charge



**Transfer Characteristics** 



Capacitance



**On-Resistance vs. Junction Temperature** 

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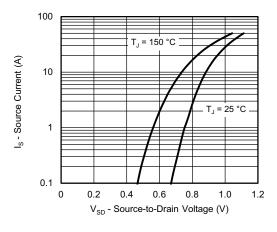
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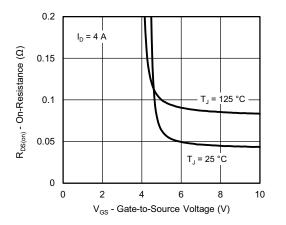
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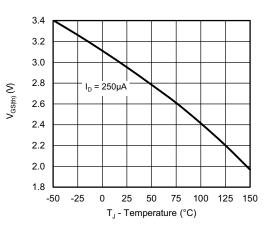
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



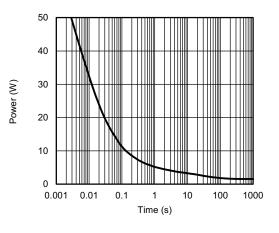
Source-Drain Diode Forward Voltage



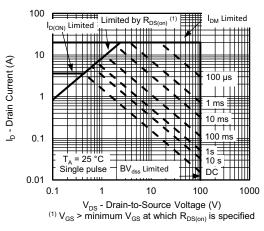
On-Resistance vs. Gate-to-Source Voltage



**Threshold Voltage** 



Single Pulse Power, Junction-to-Ambient



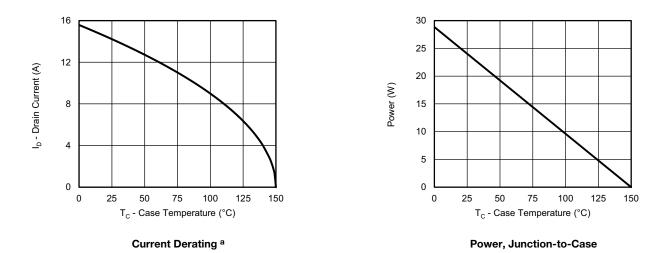
Safe Operating Area, Junction-to-Ambient

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#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



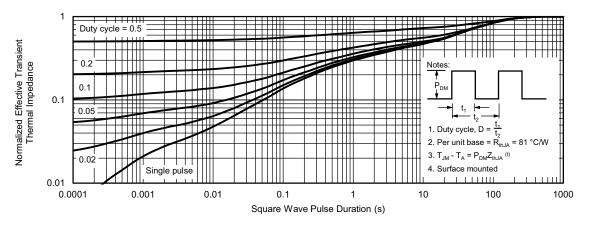
#### Note

a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

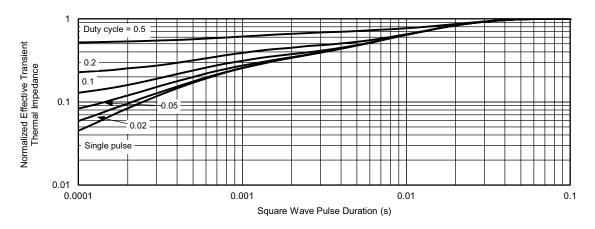
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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

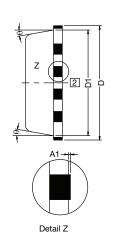
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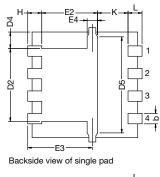
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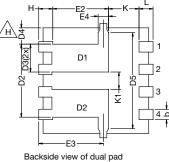


# PowerPAK® 1212-8, (Single / Dual)









Notes

1. Inch will govern

2 Dimensions exclusive of mold gate burs 3. Dimensions exclusive of mold flash and cutting burrs

DIM.	MILLIMETERS			INCHES			
DINI.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
А	0.97	1.04	1.12	0.038	0.041	0.044	
A1	0.00	-	0.05	0.000	-	0.002	
b	0.23	0.30	0.41	0.009	0.012	0.016	
С	0.23	0.28	0.33	0.009	0.011	0.013	
D	3.20	3.30	3.40	0.126	0.130	0.134	
D1	2.95	3.05	3.15	0.116	0.120	0.124	
D2	1.98	2.11	2.24	0.078	0.083	0.088	
D3	0.48	-	0.89	0.019	-	0.035	
D4		0.47 typ.	•	0.0185 typ			
D5		2.3 typ.			0.090 typ		
E	3.20	3.30	3.40	0.126	0.130	0.134	
E1	2.95	3.05	3.15	0.116	0.120	0.124	
E2	1.47	1.60	1.73	0.058	0.063	0.068	
E3	1.75	1.85	1.98	0.069	0.073	0.078	
E4		0.034 typ.			0.013 typ.		
е		0.65 BSC			0.026 BSC		
К		0.86 typ.			0.034 typ.		
K1	0.35	-	-	0.014	-	-	
Н	0.30	0.41	0.51	0.012	0.016	0.020	
L	0.30	0.43	0.56	0.012	0.017	0.022	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
θ	0°	-	12°	0°	-	12°	
W	0.15	0.25	0.36	0.006	0.010	0.014	
М	0.125 typ.				0.005 typ.		
I: S16-2667-R G: 5882	ev. M, 09-Jan-17						

Revison: 09-Jan-17

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## RECOMMENDED MINIMUM PADS FOR PowerPAK<sup>®</sup> 1212-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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